MINGYU LIU
E-mail: 2020020914016@std.uestc.edu.cn· (86) 5077898571
University of Electronic Science and Technology of China

EDUCATION

University of Electronic Science and Technology of China Chengdu, China
Bachelor of Science in Electronic Science and Technology September 2020 - June 2024

- Concentration: Solid Electronics
- Total GPA: 3.91/4.00 (89.13/100)
- Selected Coursework: Quantum Mechanics (96), Digital System Experiment EDA Technology B (98), Fundamentals of Solid-State Electronics I, Signals and Systems (90), Fundamentals of Microwave Technology A (95), Fundamentals of Microelectronic Devices

Imperial College (IC) and Nanyang Technological University (NTU) Summer Online Program
July 2022 - June 2022

- Received intensive training in IC design from Prof. Willy Sansen
- Focused on techniques related to digital IC from Prof. Goh Wang Ling
- Wrote up final reports of two courses under professional guidance

RESEARCH

University of Electronic Science and Technology of China Chengdu, China
Undergraduate Research Assistant September 2022 - September 2023
School of Integrated Circuit Science and Engineering

- Conducted a project on "A novel bandgap voltage reference based on folding compensation"
- Published a paper in *Electronics Letters* (Liu, M., Zhuang, H., Huang, L., Tao, L. and Li, Q. (2023), A novel bandgap voltage reference based on folding compensation. *Electron. Lett.*, 59.)
- Acquired extensive knowledge in integrated circuit design
- Developed skills in Cadence Virtuoso simulation techniques
- Assisted in circuit simulations for the project
- Consolidated skills in data analysis and creating visually engaging graph

University of Electronic Science and Technology of China Chengdu, China
Project Leader and Designer September 2022 - September 2023

- Worked as the project designer of "An Intelligent Ultrasonic Distance Measuring Car"
- Worked as the project designer of "Wave Energy Devices Based on Variable Step Size Search Method"
- Worked as the project designer of "An Novel Bandgap Voltage Reference Based on Folding Compensation"

HONORS & AWARDS

- Second prize of the Individual Almighty Award in National Undergraduate Advanced Mapping Technology and Product Information Modeling Innovation Competition
- Second prize of the Group Award in National Undergraduate Advanced Mapping Technology and Product Information Modeling Innovation Competition
- H prize of the 2022 Mathematical Contest in Modeling
- First prize of CUMCM (Contemporary Undergraduate Mathematical Contest in Modeling) (Provincial)
- First prize of the Second "Shanshu Cup" Mathematical Modeling Elite League
- First prize of the Individual Almighty Award in Undergraduate Advanced Mapping Technology and Product Information Modeling Innovation Competition of Sichuan Province
- Third prize of the Group Award in Undergraduate Advanced Mapping Technology and Product Information Modeling Innovation Competition of Sichuan Province

ADDITIONAL INFORMATION

Languages: Chinese (Native), English (High Intermediate, IELTS Band 7)
Skills: Circuit Simulation, Matlab Programming, C language, Industrial Product Modeling
Computer Programs: Virtuoso, Keil, SolidWorks, Matlab, Multisim, blender
Activities: Reading, Badminton, Cycling, Drawing, Concept Designing & 3D Modeling